03560.002698

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)) 	
TOMOYUKI HIROKI		:	Examiner: R. ZervigorGroup Art Unit: 1763	
Application No.: 09/742,433		:)		
Filed: December 22, 2000)		
For:	METHOD FOR MANUFACTURING LIQUID JET RECORDING HEAD) :	July 28, 2003	

Commissioner for Patents P.O. Box 1450 Alexandria, VA 022313-1450

LETTER TRANSMITTING CORRECTED DRAWINGS

Sir:

Applicant submits herewith six (6) sheets of corrected drawings to be substituted for the corresponding drawing sheets presently on file in the above-identified application. The new drawing sheets incorporate the changes in Figs. 1F^{*}, 2B, 2C, 3B, 3C, 4B, 4C, 5B, 5C, 6B and 6C to correct errors in these figures. Applicant respectfully submits that no new matter has been added.

Fig. 1F' is a bottom view of Fig. 1F (page 14, lines 15-22). However, original Fig. 1F' does not show the SiN layer 7 on both sides of the liquid chamber 2. New Fig. 1F' now correctly represents the bottom view of Fig. 1F.

Figs. 2B, 2C, 3B, 3C, 4B, 4C, 5B, 5C, 6B and 6C should illustrate the shape of the silicon wafer during and after anisotropic etching (e.g., page 14, lines 11-14).¹ However, the originally filed figures erroneously show compensation patterns being etched in the same manner and at the same time as the wafer.

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Examiner will note that the description regarding Figs. 2B and 2C is also applicable to Figs. 3B, 3C, 4B, 4C, 5B, 5C, 6B and 6C, because these figures show embodiments, which differ from the embodiment shown in Figs. 2B and 2C only in the shape of the compensation patterns.

According to the present invention, as described in the specification, a silicon wafer is over-etched using compensation patterns as a mask (e.g., page 15, line 23 - page 16, line 2). In particular, the silicon wafer is over-etched in a specific manner guided by the shape of the compensation patterns. The compensation patterns, however, are not etched in this manner at this time so that they can serve as a proper mask for over-etching (e.g., page 16, line 19 - page 17, line 15). The compensation patterns are removed by further etching (page 17, lines 16-18). Therefore, Figs. 2B, 2C, 3B, 3C, 4B, 4C, 5B, 5C, 6B and 6C have now been corrected to show only the silicon wafer during and after the etching progress.

Wherefore, Applicant respectfully requests entry of the new, corrected drawings.

Applicant's undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

ttorney for Applicant

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